Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP 2530P Mobile Thin Client
HP 2530P
Name / Model #3
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries 3 cell battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 screw driver</td>
<td>philip #1</td>
</tr>
<tr>
<td>Description #2 screw driver</td>
<td>Torx type</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove battery module
2. Remove HDD door, minicard door, RAM door, bluetooth door.
3. Remove HDD module (1.8"HDD module or 2.5 HDD module)
4. Remove expansion memory
5. Remove minicard module
6. Remove ODD assembly or 2.5" HDD module
7. Remove Keyboard
8. Remove strip cover (with power button PCB & wirless button & num lock PCB)
9. Remove LCD cable and antenna
10. Divide LCD assembly from base assembly
11. Divide logic-up assembly(with TP module & caps lock PCB & F/P module) from base assembly
12. Divide M/B(with CPU and memory and thermal module and Fan) from base assembly
13. Remove thermal module and Fan assembly from MB.
14. Remove Speaker module and indicate FFC from logic-lower assembly
15. Divide the LCD bezel from LCD assembly
16. Divide LCD panel and Hinge Bracket.
17. Separate Al skin from logic-up and strip cover and LCD cover

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove battery module
   Push the Battery Latch knob L & R and remove the battery module

2. Remove HDD door, minicard door, RAM door, bluetooth door.
   Divide the screw and remover those door
3. Remove HDD module (1.8"HDD module or 2.5 HDD module)
   Divide the HDD bracket and 1.8"HDD FFC and remove the HDD module

4. Remove expansion memory
5. Remove minicard module

6. Remove ODD assembly or 2.5" HDD module
   Divide the screws and remove the ODD module assembly
7. Remove Keyboard
   Divide the screw 5 pcs and remover the Keyboard

8. Remove strip cover (with power button PCB & wireless button & num lock PCB)
   Divide the screw and push the strip cover to remove it.
9. Remove LCD cable and antenna
   Divide the antenna and LCD cable from routing area

1. Divide the antenna from routing area

2. Divide the LVDS cable
10. Divide LCD assembly from base assembly
   Divide the screws 6pcs from Hinge base and divide it from base assembly

1. Divide the screws from Base side

2. Divide the LCD module from base assembly

1. Divide the screws from Top side
11. Divide logic-up assembly (with TP module & caps lock PCB & F/P module) from base assembly

Divide the screws 11pcs and divide it from base assembly

1. Divide the screws from Base side

2. Divide the Logic upper from base assembly

1. Divide the screws from Top side
12. Divide M/B (with CPU and memory and thermal module and Fan) from base assembly
   Divide the screws 3pcs and divide it from base assembly

13. Remove thermal module and Fan assembly from MB
   Divide the screws 2pcs and divide it from MotherBoard
14. Remove Speaker module and indicate FFC from logic-lower assembly
   Divide the screw and divide it from logic lower assembly

15. Divide the LCD bezel from LCD assembly
   Divide the screws 4pcs and divide it from LCD assembly
16. Divide LCD panel and Hinge Bracket from LCD assembly.
   Divide the screws 2pcs and divide it from LCD assembly

17. Divide Hinge Bracket from LCD panel
18. Separate Al skin from logic-up and strip cover and LCD cover

1. Divide the Al Skin from LCD cover sub assembly
1. Divide the Al_Skin from Logic upper sub assembly

1. Divide the Al_Skin from Strip Cover sub assembly